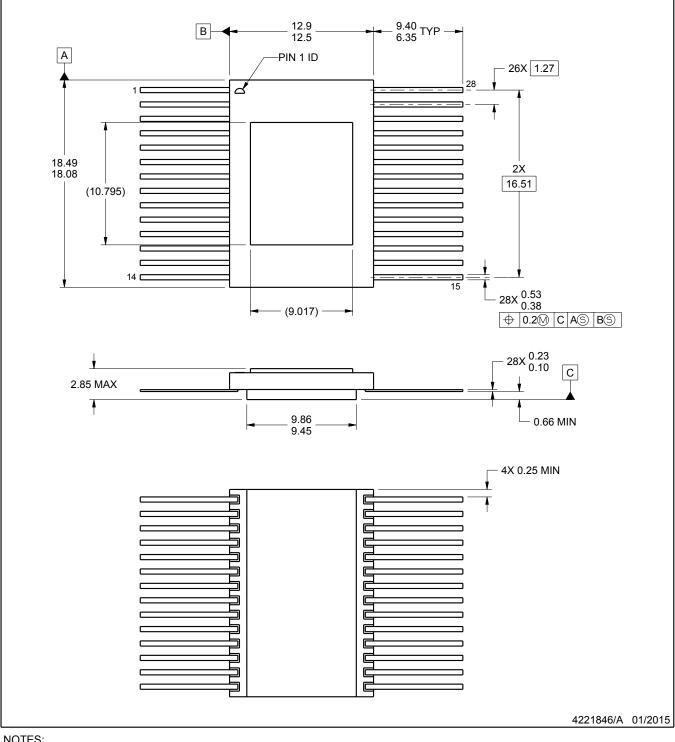
HKV0028A



PACKAGE OUTLINE

CFP - 2.85 mm max height

CERAMIC DUAL FLATPACK



NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 This package is hermetically sealed with a metal lid.
 The terminal care care later of the search of the sear

- 4. The terminals are gold plated.
- 5. Falls within MIL-STD-1835 CDFP-F11A.



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